

## Features

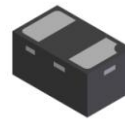
- Ultra-Low Leakage Current
- Excellent High Temperature Stability
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- +175°C Operating Junction Temperature
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound.  
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu over Copper Leadframe.  
Solderable per MIL-STD-202, Method 208 @4
- Weight: 0.001 grams (Approximate)



Top View



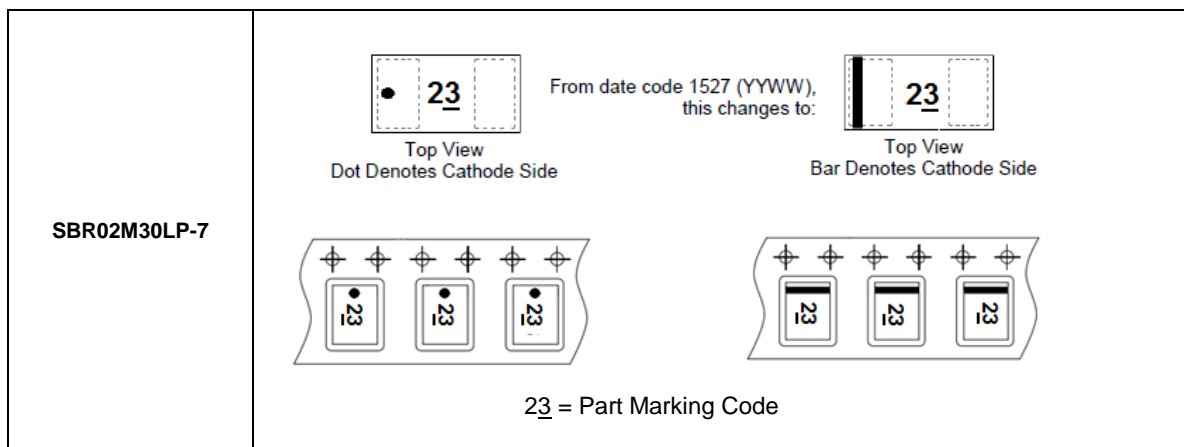
Bottom View

## Ordering Information (Note 4)

Part Number	Case	Packaging
SBR02M30LP-7	X1-DFN1006-2	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	30	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_{RM}$		
RMS Reverse Voltage	$V_{R(RMS)}$	21	V
Average Rectified Output Current (See Figure 1)	$I_O$	0.2	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	$I_{FSM}$	5.0	A

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance	$R_{\theta JS}$	18	$^\circ\text{C/W}$
Thermal Resistance Junction to Soldering (Note 5)		263	
Thermal Resistance Junction to Ambient (Note 6)			
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +175	$^\circ\text{C}$

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ.	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	30	-	-	V	$I_R = 400\mu\text{A}$
Forward Voltage Drop	$V_F$	-	0.50	0.54	V	$I_F = 0.1\text{A}, T_J = +25^\circ\text{C}$
			0.42	0.45		$I_F = 0.1\text{A}, T_J = +150^\circ\text{C}$
			0.57	0.61		$I_F = 0.2\text{A}, T_J = +25^\circ\text{C}$
			0.51	0.54		$I_F = 0.2\text{A}, T_J = +150^\circ\text{C}$
Leakage Current (Note 7)	$I_R$	-	0.1	0.5	$\mu\text{A}$	$V_R = 30\text{V}, T_J = +25^\circ\text{C}$ $V_R = 30\text{V}, T_J = +150^\circ\text{C}$
			46	150		

- Notes:
- Theoretical  $R_{\theta JS}$  calculated from the top center of the die straight down to the PCB cathode tab solder junction.
  - FR-4 PCB, 2oz. Copper, minimum recommended pad layout per <http://www.diodes.com/package-outlines.html>.
  - Short duration pulse test used to minimize self-heating effect.

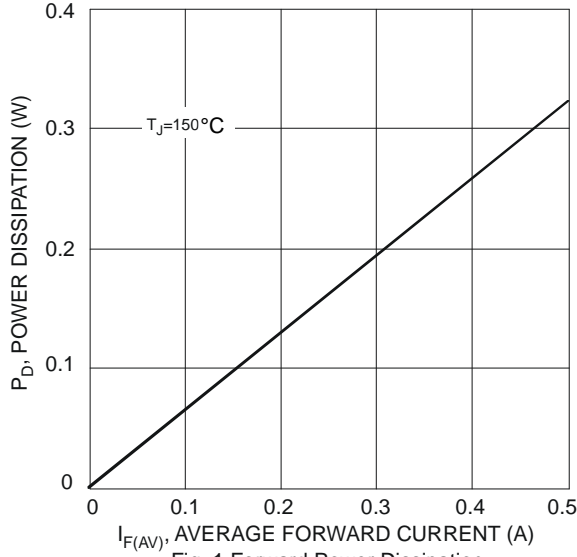


Fig. 1 Forward Power Dissipation

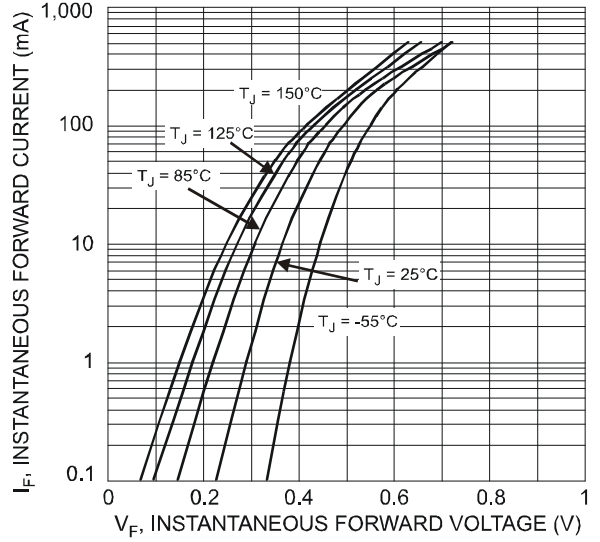


Fig. 2 Typical Forward Characteristics

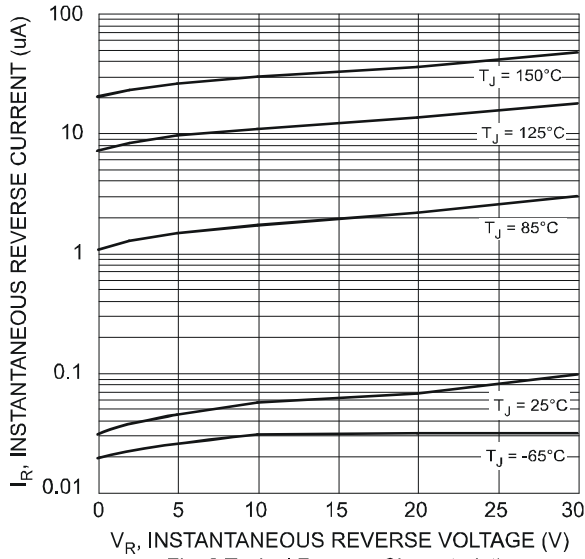


Fig. 3 Typical Reverse Characteristics

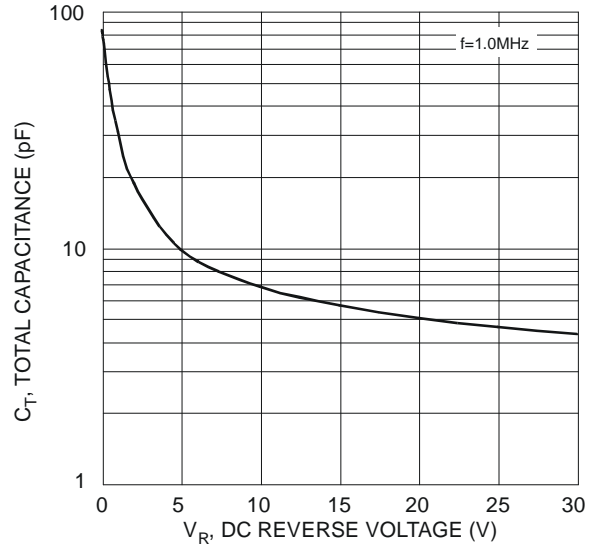


Fig. 4 Total Capacitance vs. Reverse Voltage

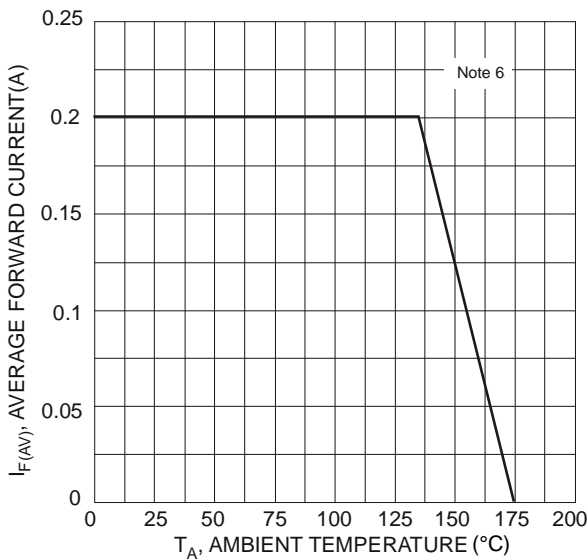


Fig. 5 Forward Current Derating Curve

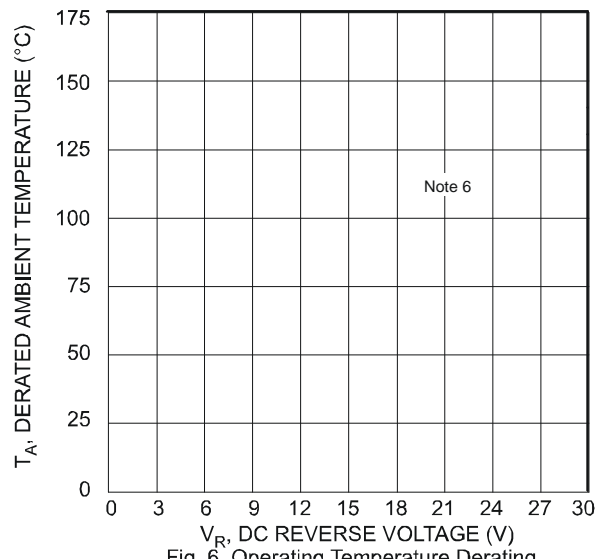
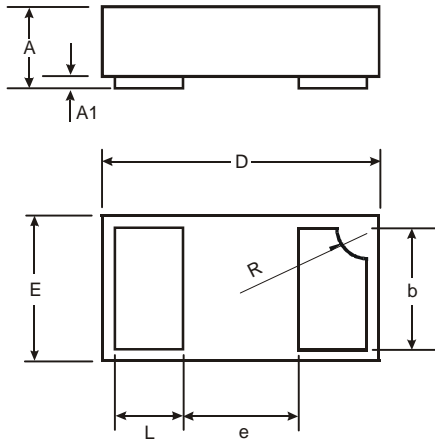


Fig. 6 Operating Temperature Derating

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-2**

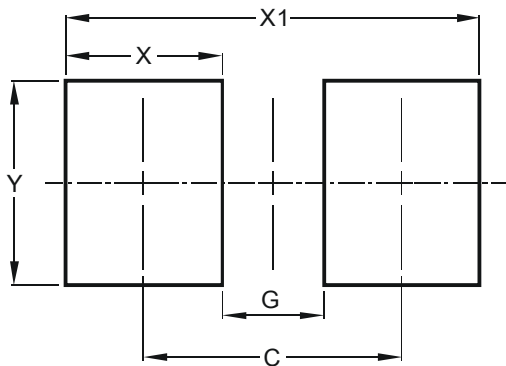


X1-DFN1006-2			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**X1-DFN1006-2**



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

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